PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tatsuo MATSUDO	06/14/2012
Kenji NAGAI	06/18/2012

RECEIVING PARTY DATA

Name:	TOKYO ELECTRON LIMITED
Street Address:	3-1, Akasaka 5-chome, Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	107-6325

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13529391

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Jaegyoo Jang

Total Attachments: 2
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OP $40.00 13529391

ASSIGNMENT

WHEREAS We,

Tatsuo MATSUDO of **c/o Tokyo Electron Yamanashi Limited, 650 Mitsuzawa Hosaka-cho, Nirasaki City, Yamanashi 407-0192, Japan**, and

Kenji NAGAI of **c/o Tokyo Electron Miyagi Limited, 1 Techno Hills, Taiwa-cho, Kurokawa-gun, Miyagi 981-3629, Japan** (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

TEMPERATURE MEASURING SYSTEM, SUBSTRATE PROCESSING APPARATUS AND TEMPERATURE MEASURING METHOD

which claims priority to **Japanese Patent Application No. 2011-140642, filed on June 24, 2011, Japanese Patent Application No. 2011-239002, filed on October 31, 2011, U.S. Patent Application No. 61/523447, filed on August 15, 2011**, and **U.S. Patent Application No. 61/557958, filed on November 10, 2011**, and for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **TOKYO ELECTRON LIMITED** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Japan, having a place of business at **Address: 3-1 Akasaka 5-chome, Minato-ku, Tokyo 107-6325, Japan**, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: June 14, 2012 Tatsuo Matsudo
Tatsuo MATSUDO

Date: June 18, 2012 Kenji Nagai
Kenji NAGAI

Date:

Date: